

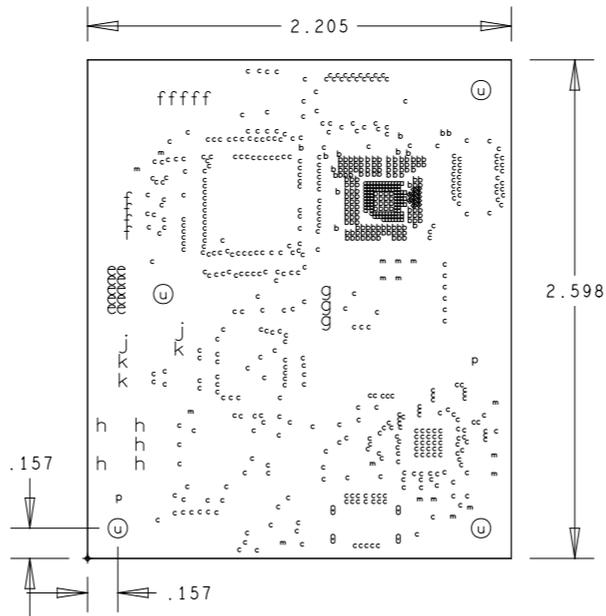
LAYER	THICKNESS	STACKUP	MATERIAL	DESCRIPTION
LAYER 1	0.0005 0.0020		SOLDERMASK	1/2oz Sig (Std Plt) - 50 Ohms - 0.005 width 68 Ohms - 0.004 width 100 Ohms Differential - 0.0041 width/0.00575 Space
LAYER 2	0.0027		FR408H	
LAYER 3	0.0006 0.0040		FR408H	1/2oz P/G FR408H
LAYER 4	0.0006		FR408H	1/2oz SIG - 50 Ohms - 0.005 width 100 Ohms Differential - 0.00425 width/0.00575 Space
LAYER 5	0.0072		FR408H	
LAYER 6	0.0012 X.XXXX		FR408H	1oz P/G FR408H
LAYER 7	0.0012 0.0027		FR408H	1oz P/G FR408H
LAYER 8	0.0006 0.0040		FR408H	1/2oz SIG - 50 Ohms - 0.005 width 100 Ohms Differential - 0.00425 width/0.00575 Space
LAYER 9	0.0006		FR408H	1/2oz P/G
LAYER 10	0.0027		FR408H	
LAYER 11	0.0020 0.0005		SOLDERMASK	1/2oz Sig (Std Plt) - 50 Ohms - 0.005 width SOLDERMASK

DRILL CHART: TOP to LY4GND

ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
a	4.0	+0.0/-4.0	PLATED	106
◆	4.01	+0.0/-4.0	PLATED	12

DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
b	6.0	+0.0/-6.0	PLATED	155
c	8.0	+0.0/-8.0	PLATED	442
m	24.0	+3.0/-3.0	PLATED	17
e	25.59	+1.97/-1.97	PLATED	10
f	27.72	+2.01/-2.01	PLATED	9
g	31.65	+1.97/-1.97	PLATED	3
h	35.43	+2.01/-2.01	PLATED	5
k	40.0	+2.0/-2.0	PLATED	3
j	40.0	+2.01/-2.01	PLATED	2
p	40.0	+3.0/-3.0	PLATED	2
⊙	94.49	+2.99/-2.99	NON-PLATED	4
B	47.24x19.69	+2.0/-2.0	PLATED	4



FAB NOTES:

- ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE NOTED. ALL BOARD OUTLINE DIMENSION TOLERANCES ARE +/- .010".
- THE PWB SHALL BE FABRICATED TO IPC-6012 CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
- BOARD MATERIAL SHALL BE ISOLA FR408HR OR EQUIVALENT, ROHS AND REACH COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. ROHS AND REACH CERTIFICATE OF CONFORMANCE SHALL BE DELIVERED WITH EACH LOT. ROHS TO BE MARKED ON THE FINISHED BOARD.
- ALL BOARDS MUST MEET OR EXCEED UL94V-0 REQUIREMENTS. PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER.
- MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .002 INCH.
- OVERALL BOARD THICKNESS TO BE .062 +/- .10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER. DI-ELECTRIC MATERIAL HEIGHT CAN BE UPDATED IN FAB HOUSE BASED ON MATERIAL AVAILABILITY
- MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
- ANY DISCREPANCY BETWEEN FABRICATION PRINT AND THE ACTUAL FABRICATION DATA MUST BE REVIEWED AND APPROVED BY ASSEMBLY SHOP.
- 4 MIL & 4.01MIL BLIND VIAS TO BE FILLED WITH NON CONDUCTIVE EPOXY AND PLATED OVER COPPER. SURFACE SHOULD BE FLAT ON TOP SIDE.

PROCESS NOTES:

- EXCEPT AS NOTED BELOW, PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD, NICKEL 100 MIN MICROINCHES THK GOLD 2-6 MICROINCHES THK.
- FABRICATOR TO REMOVE UNUSED PADS ON INTERNAL LAYERS.
- MINIMUM TRACE/SPACE UNDER U1 IS .003/.003
- APPLY LDI SOLDERMASK. COLOR: RED. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H. CURRENT REV. SOLDERMASK SHALL BE COMPATIBLE WITH SAC305 OR EQUIVALENT SOLDER ALLOY AND SOLDER FLOAT BATH TEMPERATURE OF 288°C.
- SOLDERMASK ARTWORK HAS ZERO (0) OVERSIZED PADS. FABRICATION VENDOR IS ALLOWED TO ADJUST THE COMPONENT SOLDERMASK PADS TO MEET THEIR TOOLING REQUIREMENTS WHILE MAINTAINING WEBBING BETWEEN ADJACENT PADS.
- SOLDERABILITY SHALL BE IN ACCORDANCE WITH IPC/EIA J-STD-003A, WITH SOLDER BATH TEMPERATURE OF 250°C +/- 5 C FOR DIP OR ROTARY TEST.
- APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: WHITE.
- BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
- VENDOR MUST SUPPLY PANELIZED PASTE LAYERS TO ASSEMBLY SHOP FOR PASTEMASK STENCIL.

CUSTOMER NAME			TEXAS INSTRUMENTS		DRAWN		SVT	
BOARD NAME			DLPDLCR160CPEVM		DESCRIPTION			
					DRILL DRAWING			
BOARD NO.	REV	DATE	PRJ#	SH	OF			
DLP094	B	03-NOV-2023	TIDLDP-309772-01	17	20			